## **FPGAs in Space**

Lukas Liedl

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- History
- Challenges in space
- Problems caused by radiation
- Mitigations
- Manufacturers of space qualified FPGAs
- Lessons learned

# History

- Used in data processing unit of SAMPEX spacecraft in *1992*
- Six A1020 chips for redundancy
- 547 logic cells



Figure 1: Sampex data processing unit [2]

### Why use FPGA in space?

- Space missions are getting more and more complex
- Comparison to microcontrollers:
  - More efficient in energy and space consumption
  - *Higher computing power* (parallelism)
  - More expensive, longer development times
- Comparison to ASICs:
  - Less efficient in energy and space consumption
  - Less computing power
  - Less expensive, shorter time to launch
- Conclusion: FPGAs are the sweet-spot between ASICs and  $\mu$ Cs

### FPGA vs. ASIC per mission

- Immarsat 4: Communication satellite, launched in 2008
- Bepicolombo: Orbiter, launched in 2018



Figure 2: ICs per space mission [1]

#### FPGA vs. ASIC over time



Figure 3: IC overview vs. launch date [1]

#### IC usage vs. cost



Figure 4: IC usage vs. cost [1]

## **Challenges in space**

- Exposure to radiation
- Temperature
- Weight and space limits
- Power consumption

- Emitted by the sun
- Non-ionizing radiation can be shielded by the right materials
- Ionizing radiation can't be shielded, charged particles travel through substances
- Change in behaviour of semiconductors

## Problems caused by radiation

- High-energy ionizing radiation creates electron holes within the oxide of MOS transistors.
- Charge is built up within the oxide
- Changes in *threshold voltage* and timing
- Might lead to total failure



#### Figure 5: Radiation in MOS oxide [3]

## Single event latchup (SEL)

- CMOS has intrinsic transistors in substrate
- Creates latch-up circuit
- Radiation might trigger the latch-up
- Low impedance connection between  $V_{dd}$  and gnd leads to permanent damage



Figure 6: Latch-up circuit in CMOS [4]

### Single event upset (SEU)

- When radiation passes through device, charge is transferred between nodes
- If critical charge is exceeded, a change in voltage level happens
- This results in a *bitflip*
- Temporal error



Figure 7: Example of SEU in combinational logic [5]

- Because of its large space consumption, memory is very vulnerable to bitflips
- Especially upsets in *configuration memory*, which takes most of the memory space, will lead to different logic behaviour
- Types of configuration memory:
  - Antifuse: only programable once, immune to SEU
  - Flash: limited programming cycles, immune to SEU
  - SRAM: unlimited programming cycles, vulnerable to SEU

### **FPGA** Architecture Vulnerabilities

• Example bitflip in configuration memory:



Figure 8: Bitflip example [6]

Mitigations

### Triple modular redundancy (TMR)

- Can be realized within single FPGA or on three seperate FPGAs
- Single SEU allowed in one branch
- *Big overhead* in space and power consumption



Figure 9: Triple modular redundancy [6]

### **Configuration scrubbing**

- Frequently check integrity of configuration in SRAM by comparing to source memory
- Repair upsets when difference is noticed
- No guarantee for protection against temporal errors
- Often used in combination with TMR



Figure 10: Hybrid scrubbing [7]

- Special manufacturing processes for MOS technology
- Thinner oxide to reduce probability of electron holes
- Isolating wells from the substrate to prevent latch-up
- Different transistor shapes and sizes

## Manufacturers of space FPGAs

| ASIC      | FPGA              | Microprocessor | Standard ASIC |
|-----------|-------------------|----------------|---------------|
| Aeroflex  | ACTEL (Microsemi) | Aeroflex       | Aeroflex      |
| AMIS      | Aeroflex          | ATMEL          | ATMEL         |
| ATMEL     | ALTERA            | DYNEX          | DYNEX         |
| Honeywell | ATMEL             | FREESCALE      | HONEYWELL     |
| INFINEON  | XILINX            | HONEYWELL      | IBM           |

Figure 11: IC manufacturers for space application [1]



- Radiation Tolerant (RT) Kintex UltraScale XQRKU060
  - First 20nm (predecessor was 65nm) FPGA for space applications
  - 726000 (predecessor had 81900) logic cells
  - 38Mb (predecessor had 12Mb) of memory
  - Uses TMR and external scrubbing

| Symbol   | Description   | Min | Тур    | Max | Units            |
|----------|---|-----|--------|-----|------------------|
| TID      | Total Ionized Dose (GEO)  | -   | 100    | 120 | Krad (Si)        |
| SEL      | Single-Event-Latch-Up Immunity  | +   | 80     | -   | MeV-cm2/mg       |
| SEUCRAM  | Single-Event Upset in Configuration RAM (GEO)                                       | -   | 1.0e-8 | -   | Upset/bit/day    |
| SEUBRAM  | Single-Event Upset in Block RAM (GEO)   | -   | 8.5e-9 | -   | Upset/bit/day    |
| SEFICRAM | Single Event Functional Interrupt Orbital Upset Frequency - Configuration RAM (GEO) | -   | 4.5e-4 | -   | Upset/device/day |

Figure 12: Radio tolerance of QRKU060 [8]

### Microchip

- RT PolarFire
  - 28nm process technology
  - 481000 logic cells
  - 33Mb of memory
  - Synthesis support for TMR and scrubbing
- Radiation tolerance:
  - 100 Krad total ionizing dose
  - No SEUs in configuration memory
  - Data upset rate of  $10^{-10} errors/bit/day$

## **Lessons learned**

- NASA Wide Field Infrared Explorer (WIRE) spacecraft was launched in 1999
- Synchronous reset to force FPGA logic into a safe state
- Start-up time of crystal oscillator was not considered
- Circuit was in non-deterministic state during this time
- Problem: lack of documentation of FPGA behaviour, default states were not considered
- WIRE went out of hydrogen and could not perform operations

- In 2001 European Space Agency (ESA) set up task force to perform investigations on FPGA implantations
- Results:
  - Designers unaware of how synthesis tools work
  - Little effort in testing of SEU correction implementation
  - Lack of documentation for FPGA behaviour
  - Reviews on completed designs are extremely costly

- FPGAs have been in space since 1990s
- Trends show rise in FPGA vs. ASIC use
- FPGA chips need to be protected against radiation:
  - On physical level (transistors, shielding)
  - $\bullet$  Single event correction: TMR, scrubbing, ECC
- Manufacturers improving technologies
- Mistakes made in the past

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